



Technical Data Sheet

DOWSIL™ TC-5080 Thermal Grease

FEATURES & BENEFITS

- Good thermal conductivity
- Low oil bleed
- Stable at high temperatures

COMPOSITION

- Thermally conductive fillers
- Siloxane polymer matrix

One-part, white, non-curing, thermally conductive compound

APPLICATIONS

- DOWSIL™ TC-5080 Thermal Grease is suitable for use as a thermal interface material for lighting assemblies, telecom equipment, consumer devices, power supplies and power components for transportation.

TYPICAL PROPERTIES

Specification Writers: These values are not intended for use in preparing specifications.

| Property | Unit | Result |
|----------------------------|--------------|---------|
| One part or Two part | - | One |
| Color | - | White |
| Viscosity | cP | 836000 |
| | mPa-sec | 836000 |
| | Pa-sec | 836 |
| Extrusion Rate | grams/min | 1053 |
| Flow Rate (Slump) | mm | 4.5 |
| Specific Gravity (Uncured) | - | 2.1 |
| Oil Bleed – 150°C/24hrs | % | <0.01 |
| Thermal Conductivity | btu/hr-ft-°F | 0.58 |
| | W/mK | 1 |
| Dielectric Strength | volts/mil | 220 |
| | kV/mm | 8.7 |
| Volume Resistivity | ohm*cm | 2.9E+15 |

DESCRIPTION

Dow thermally conductive compounds are grease like silicone materials, heavily filled with heat-conductive metal oxides. This combination promotes high thermal conductivity, low bleed and high-temperature stability. The compounds are designed to maintain a positive heat sink seal to improve heat transfer from the electrical device and PCB system assembly to the heat sink or chassis, thereby increasing the overall efficiency of the device.

PCB system assemblies are continually designed to deliver higher performance. Especially in the area of consumer devices, there is also a continual trend towards smaller, more compact designs. In combination these factors typically mean that more heat is generated in the device. Thermal management of PCB system assemblies is a primary concern of design engineers. A cooler device allows for more efficient operation and better reliability over the life of the device. As such, thermally conductive compounds play an integral role here.

Thermally conductive materials act as a thermal “bridge” to remove heat from a heat source (device) to the ambient via a heat transfer media (i.e. heat sink). These materials have properties such as low thermal resistance, high thermal conductivity, and can achieve thin Bond Line Thicknesses (BLTs) which can help to improve the transfer of heat away from the device.

APPLICATION METHODS

- Screen print
- Stencil print
- Needle dispense

SOLVENT EXPOSURE

In general, the product is resistance to minimal or intermittent solvent exposure, however best practice is to avoid solvent exposure altogether.

USABLE LIFE AND STORAGE

The product should be stored in its original packaging with the cover tightly attached to avoid any contamination. Store in accordance with any special instructions listed on the product label. The product should be used by the indicated Exp. Date found on the label.

HANDLING

PRECAUTIONS

PRODUCT SAFETY

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DOWSIL™ TC-5080 Thermally Conductive Compound

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